

Fig. 1(A)

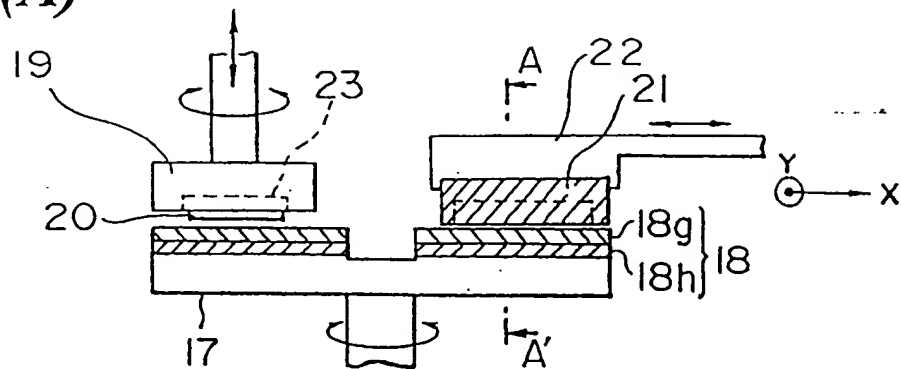


Fig. 1(B)

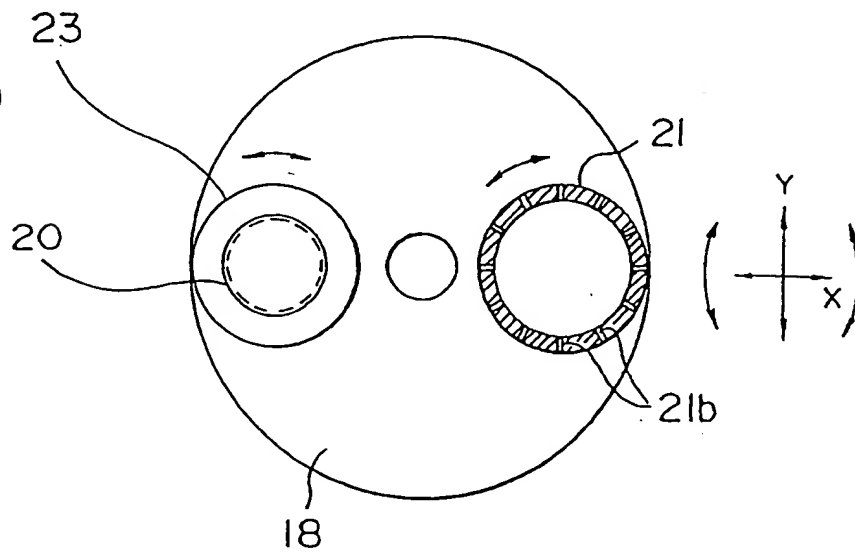
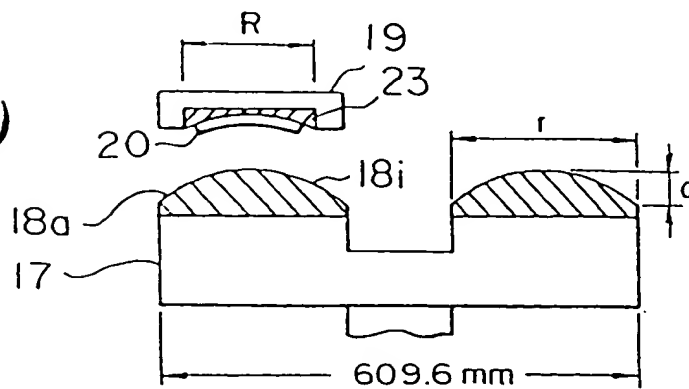


Fig. 2(A)



200001-12409680

Fig. 2(B)

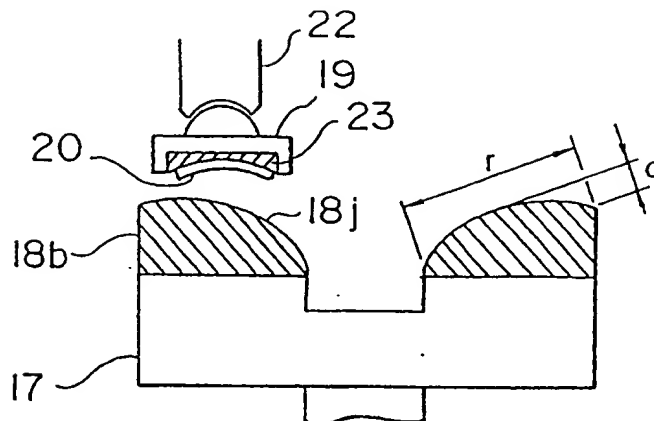
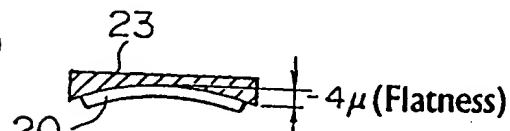


Fig. 2(C)



Wafer 6 inch ϕ ,
($r \approx 280$ mm, Flatness 4μ Incase of $d = 4 + 8\mu$)

Fig. 2(D)

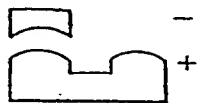


Fig. 2(E)



Fig. 3

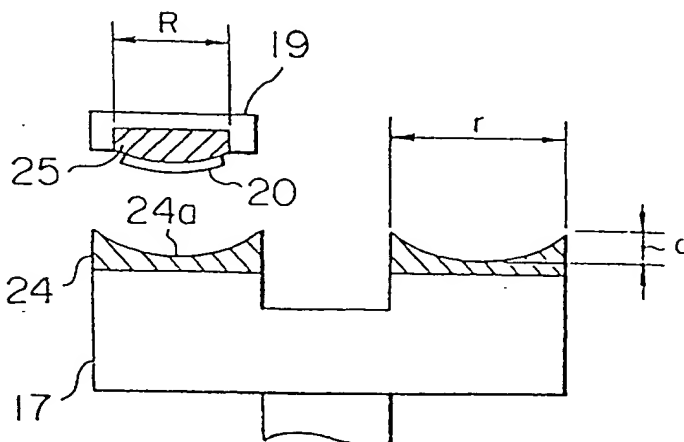


Fig. 4(A)

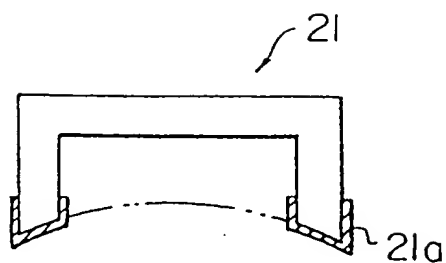


Fig. 4(B)

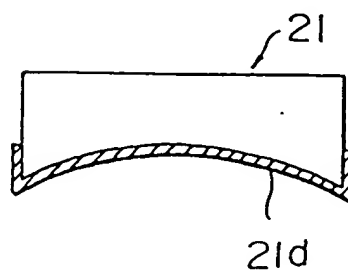
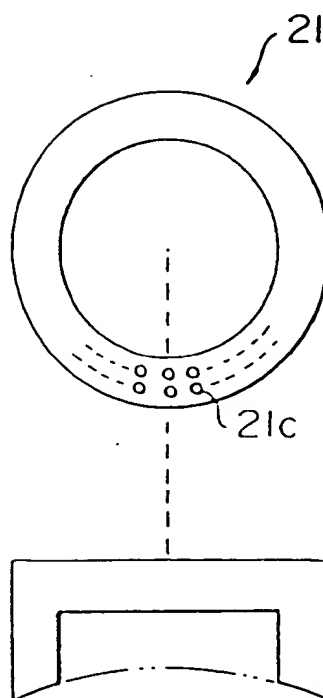


Fig. 4(C)



266207 "TECH 9680

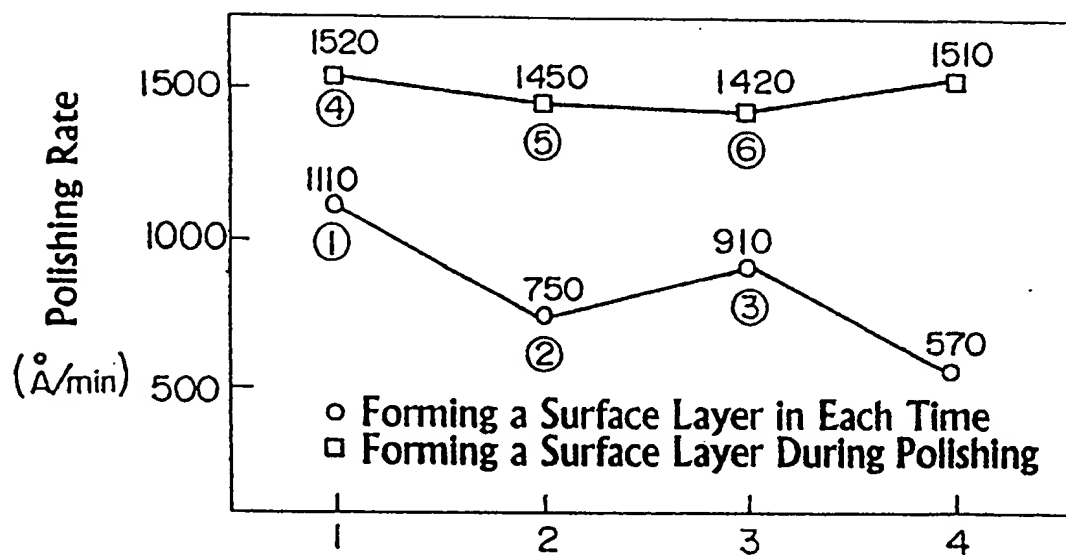
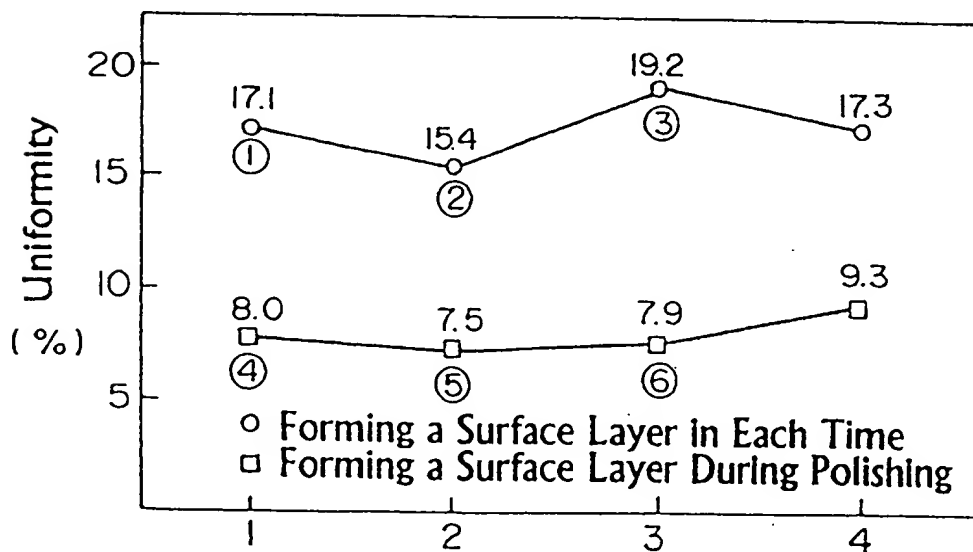
Fig. 5*Fig. 6*

Fig. 7

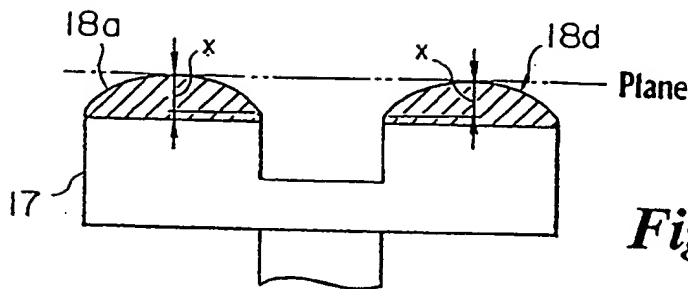
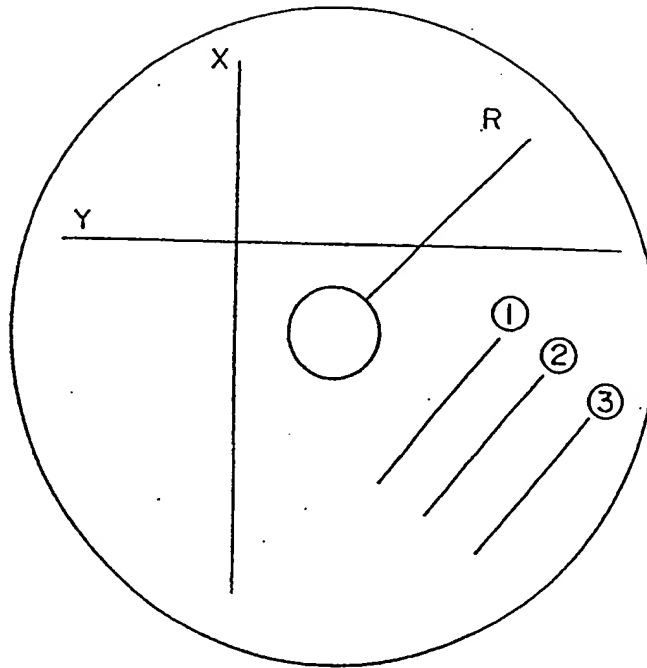


Fig. 8(A)

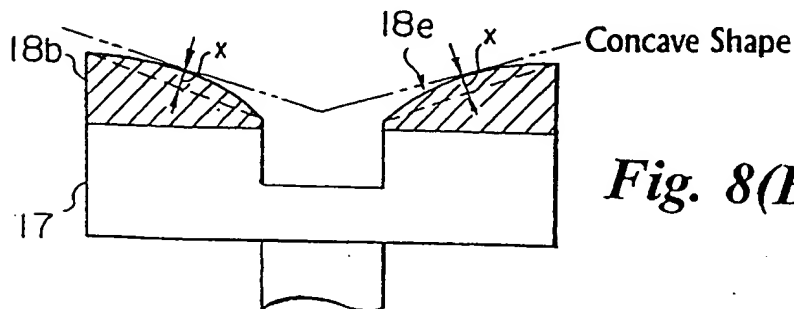


Fig. 8(B)

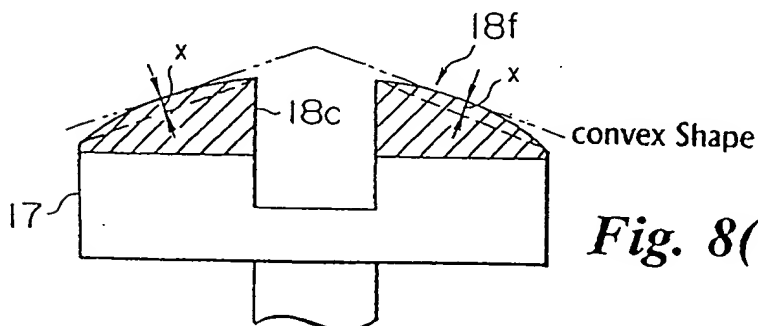


Fig. 8(C)

08960431.102697
266207-TE409680

Fig. 9(A)

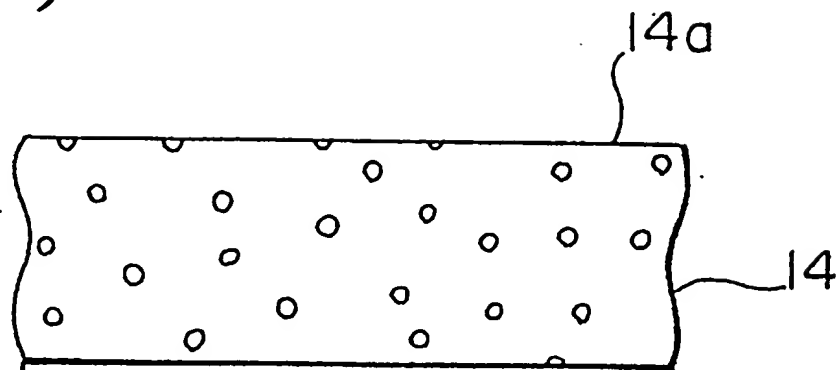
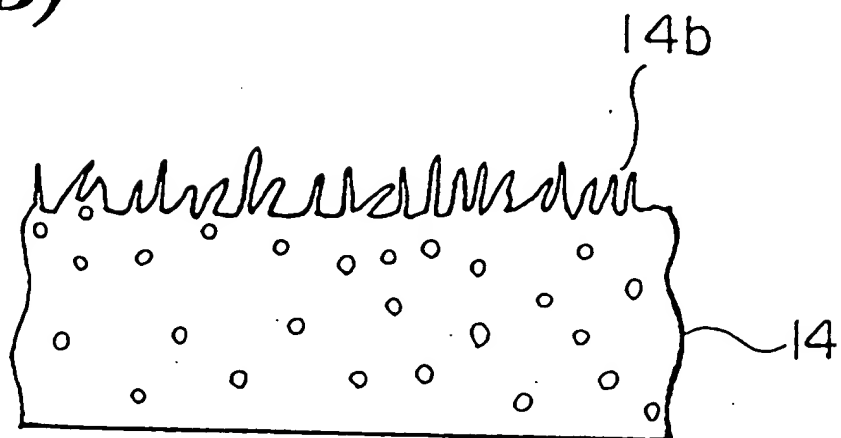


Fig. 9(B)



0296041.102997
266207 FEB 25 1997

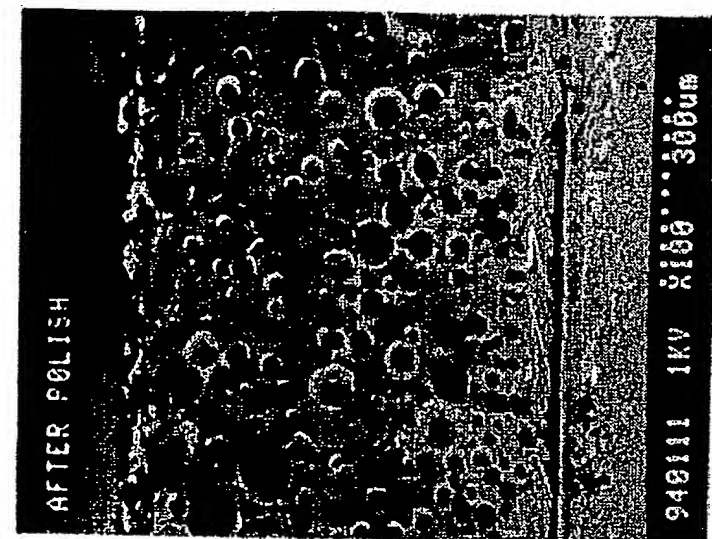


FIG. 12

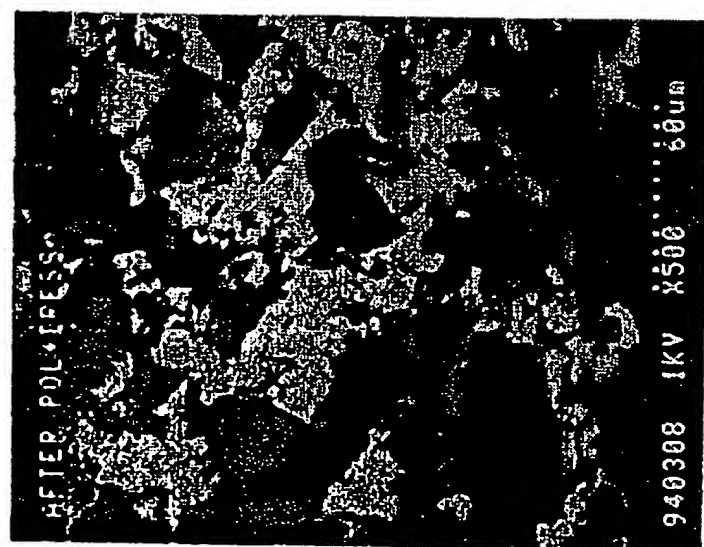


FIG. 11

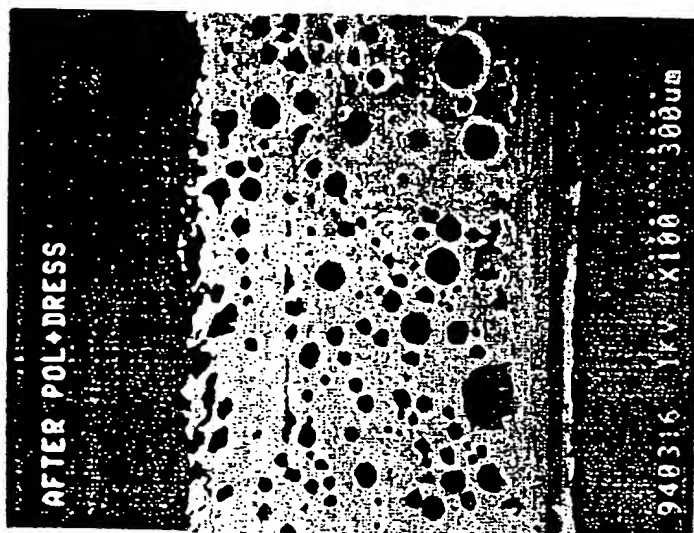


FIG. 10

20000109680



FIG.13

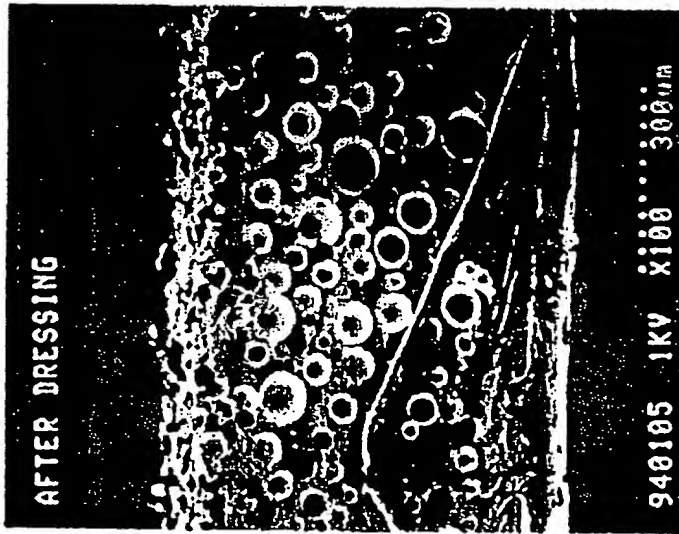


FIG.14

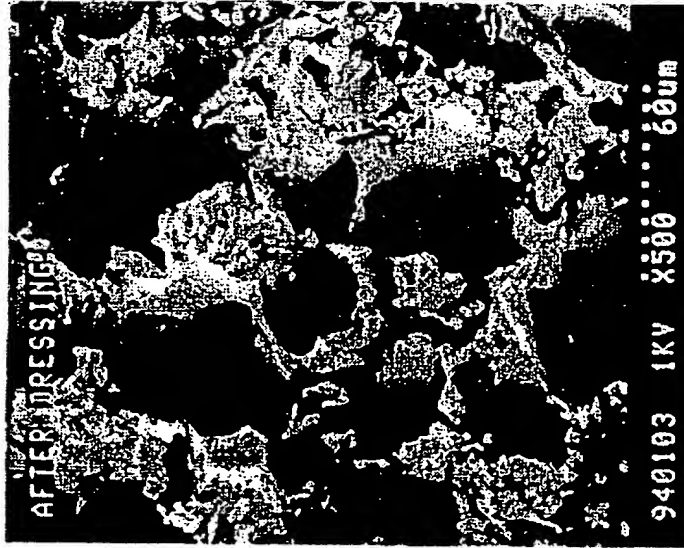


FIG.15

26620T"TE409680

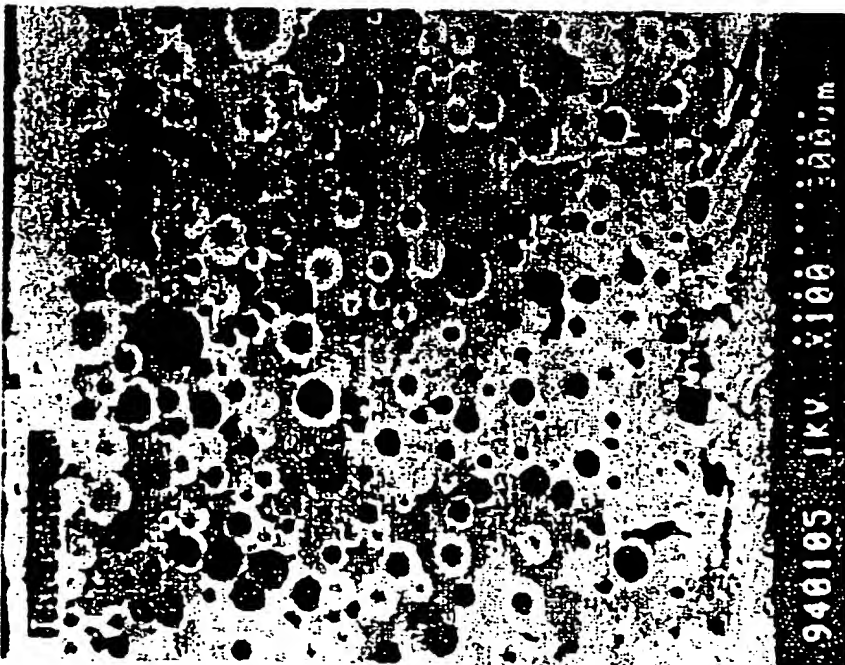


FIG. 16

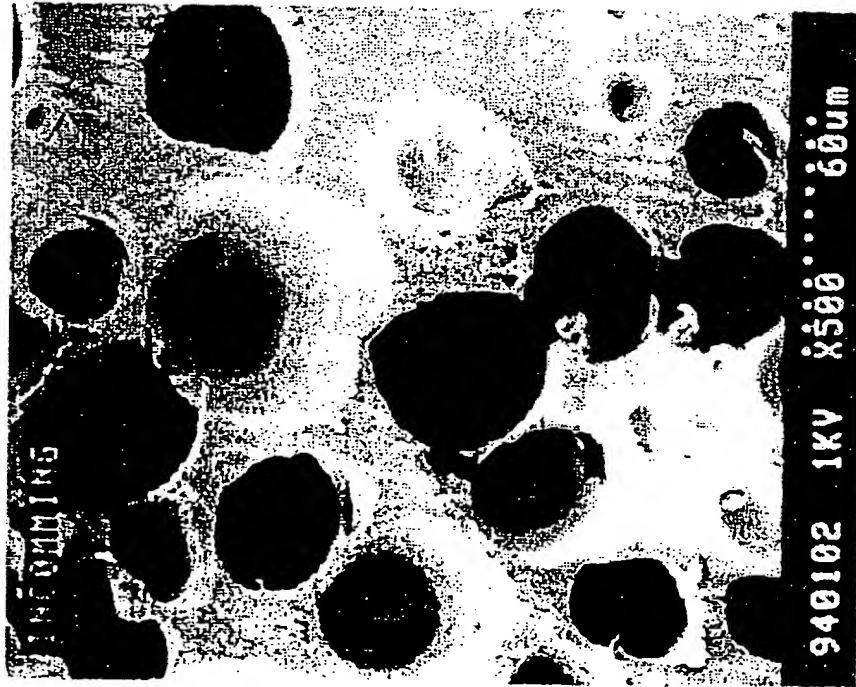


FIG. 17

Fig. 18

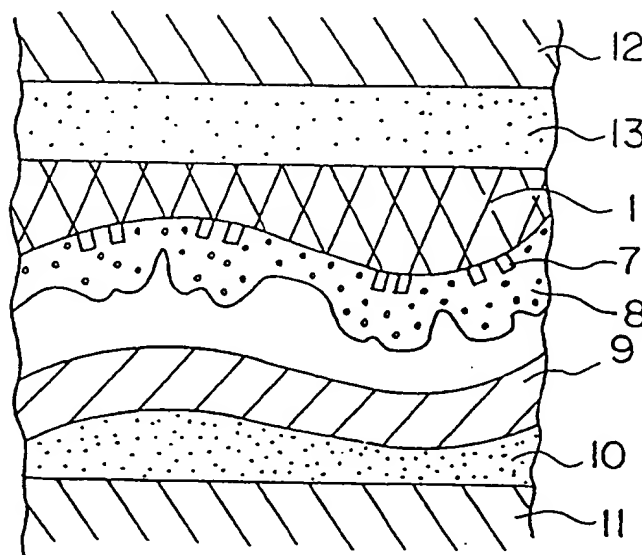


Fig. 19

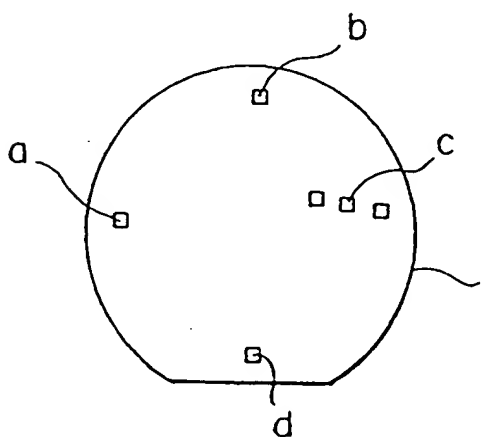
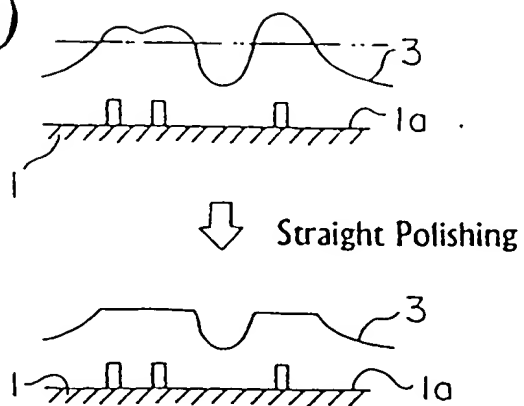


Fig. 20(A)



08960431-102997

Fig. 20(B)

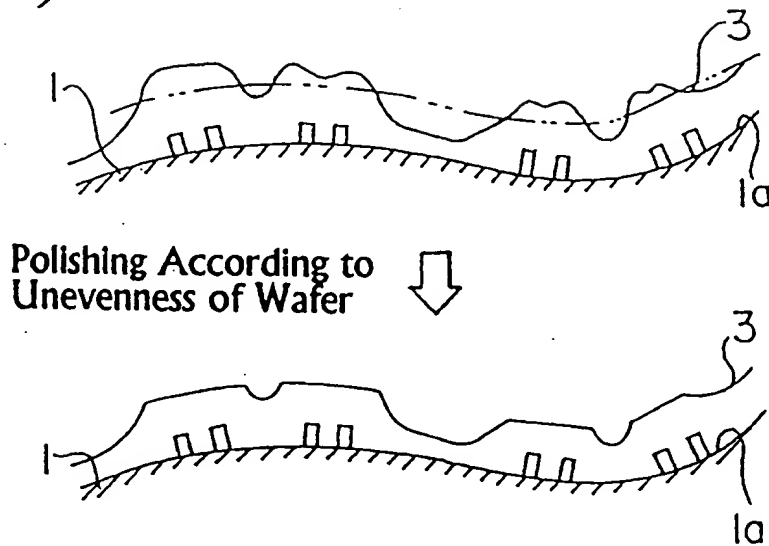


Fig. 21(A)

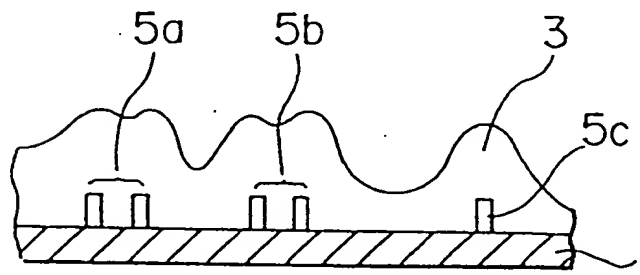
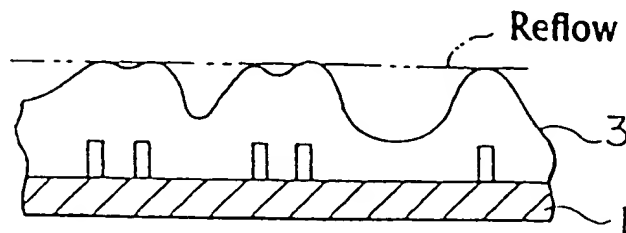


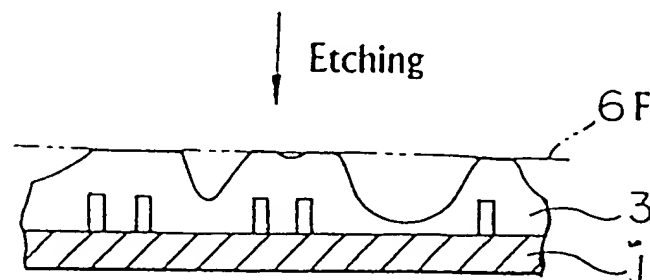
Fig. 21(B)



Etching

6 Flattening

Fig. 21(C)



08960431-102997

Fig. 22(A)

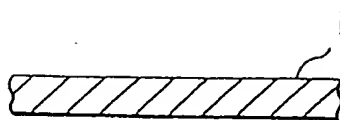


Fig. 22(B)

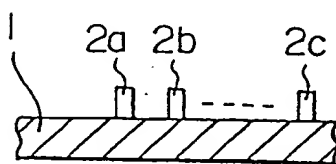


Fig. 22(C)

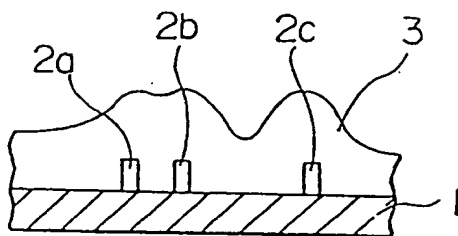


Fig. 22(D)

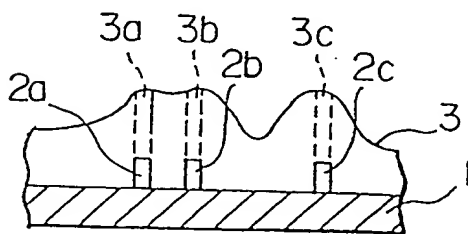
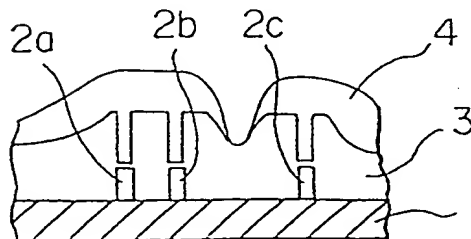


Fig. 22(E)



08960431-10297
266207-TEH09680